

Tool ID: 318
Tool Location: 110

Equipment Information Sheet

AJA Sputter Deposition - 3

Manager: Tom Pennell 607-254-4309
Backup: Shilling Du 607-254-4907
Backup: Philip Schneider 607-254-4931

Calls to staff phones will be automatically forwarded to their cell phones during accessible hours. At other times leave a message or send them an email.

SAFETY

USAGE RESTRICTIONS

- Users must remain in the cleanroom near the tool when the power supplies are in operation

SCHEDULING/SIGN-UP RESTRICTIONS

Minimum Tool Time: 15 minutes

- Maximum 4 hour block reservations any time
- Must leave a 4 hour block between reservations
- Maximum of 12 hours reserved in advance at any time

MATERIALS COMPATIBILITY CATEGORY

Tool Category 4: Glass and Metal Categories

Allowed	Not Allowed
Tool category 1/1E, 2, and 3 materials	
Silicon Based Substrates and Films	No CNF Class A metals
III/V compound Semiconductors	No Exposed CNF Group B metals- <i>metals can be buried/covered with staff approval</i>
Glass Substrates	Cannot be used as an etch stop
PECVD and ALD Films	
Buried Class B Metals with approval	
Organic/Bio Materials prepped w/o Salt Buffers	
Cured organics and baked Photoresist	No High Vapor pressure materials

High Vapor Pressure Metals and Compounds are materials that have a vapor pressure above 1e-6 Torr at 400 C.

Additional Material Restrictions and Exceptions

- Tool users should discuss their specific materials needs with staff
- Due to laboratory material restriction policies, once a sample uses this chamber it may be restricted from other vacuum systems within the facility including etching and deposition systems.

Last Updated: 04/15/2026